

ABSTRACT

Please replace the existing Abstract with the following new Abstract:

--A circuit board manufacturing method including the steps of forming a through hole on an insulator layer and then filling the through hole with a conductive paste; dispersing and forming a protective agent on an adhesion surface of a conductor foil so as to include adhesion surface regions where the protective agent does not exist; sticking the conductor foil to the insulator layer; and abutting a plurality of conductive powders constituting the conductive paste and the conductor foil to each other through the adhesion surface regions by means of heating and pressurizing the insulator layer and conductor foil.--